

Customer Process Change Notification Form PCN-2010-407

Part Information

Cirrus Logic Part # / Quantity

CS5533-ASZ	CS5524-ASZR	CS5534-ASZ	CS5372A-ISZR
CS5533-ASZR	CS5528-ASZ	CS5534-ASZR	CS5371A-ISZ
CS5523-ASZ	CS5528-ASZR	CS5371-BSZ	CS5371A-ISZR
CS5523-ASZR	CS5533-ASZ	CS5371-BSZR	
CS5534-BSZ	CS5533-ASZR	CS5372-BSZ	
CS5534-BSZR	CS5534-ASZ	CS5372-BSZR	
CS5524-ASZ	CS5534-ASZR	CS5372A-ISZ	

PCN Effective Date: Lot Effective Date:

Cirrus P/N Change: Yes No (Contact the sales representative for availability of samples if applicable)

If yes, provide new part number:

Additional Part Number (use if more space is needed)

[Click here to attach a file](#)

Package Mark Change: Yes No

If Yes, briefly explain:

The assembly identifier will change from NA to AA.

xxNAxxxxxyww to xxAAxxxxxyww

Country of origin will change from Philippines to China.

[Any Fab, Assembly, or Design changes results in pack mark changes, please provide detail]

- Reason for Change:**
- | | |
|--|--|
| <input type="checkbox"/> Design/New Rev | <input type="checkbox"/> Fab Process |
| <input type="checkbox"/> Assembly Site | <input checked="" type="checkbox"/> Additional Assembly Source |
| <input type="checkbox"/> Fab Site | <input type="checkbox"/> Assembly Process |
| <input type="checkbox"/> Other (Specify) | <input type="checkbox"/> Additional Fab Source |

- Description of Change:**
- | | |
|---|--|
| <input type="checkbox"/> Fix Errata | <input type="checkbox"/> Yield Enhancement |
| <input type="checkbox"/> Fix Known Bug | <input type="checkbox"/> Performance Improvement |
| <input checked="" type="checkbox"/> Other (specify) | |

Addition of assembly site ANST (Wuxi, PRC) and reduction of bond wire diameter for the above listed devices assembled in 24 LD SSOP.

Summary of Bill of Material Change:

24 SSOP CURRENT - AMKOR NEW SITE - ANST

Additional Information

 [Click here to attach a file](#)

Quality and Reliability Impact:

Qualification Data Required? Yes No

Additional Information

 Reliability Report
QRR100805.pdf
27.86 KB

Data Sheet Change Required? Yes No

If Yes, briefly explain:

Additional Information

 [Click here to attach a file](#)

Software Change Required? Yes No

If Yes, briefly explain:

Additional Information

 [Click here to attach a file](#)

Customer Acknowledgement and Agreement

Acknowledged and Agreed as of the Date written below:

Customer Company _____
Name:

Customer Contact _____
Name:

Title: _____

Signature: _____

Date:

Customer Agreed Customer Reject Not Applicable

Customer Comments:

Description of change:

Addition of assembly site ANST (Wuxi, PRC) and reduction of bond wire diameter for the above listed devices assembled in 24 LD SSOP.

Summary of Bill of Material Change:

24 SSOP	CURRENT - AMKOR	NEW SITE - ANST
Mold Compound	Sumitomo G700	no change
Die Attach	Ablebond 84-1 LMISR4	Ablebond 8290
Wire	1.2 mil Au	1.0 mil Au
Leadframe	0.154" x 0.232"	no change
Finish	Matte Sn, 100%	no change



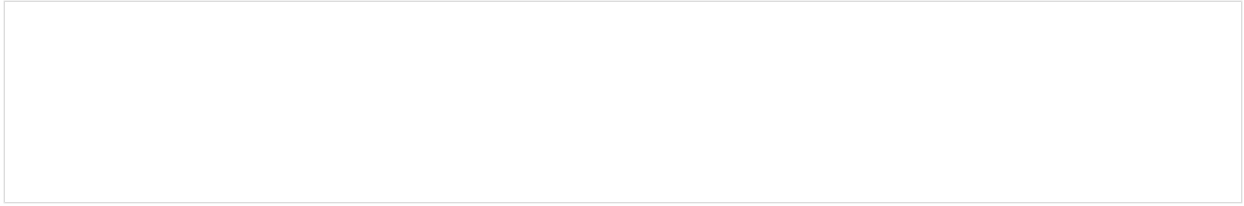
Qualification Reliability Report


Report: QRR100805
Date: 8/31/2010
Approved by: Mike Klucher

Purpose	Results
Qualification of 24 SSOP package family at ANST with 16.6mm ² die area. This QUAL can be used to qualify devices that are smaller or up to 10% larger in the same package.	Qualification successful.

Background Information					
Assembly:	ANST (China)	Package Family:	24 SSOP	Lead Finish:	Pb-free
Qual Vehicle:	CS5534				

Stress Name	Method	Conditions	Lot	Read Point	Results (Fail/Sample)
Precondition MSL-3	JESD22-A113	24HR 125 °C Bake 192HR 30°C/60%RH Soak 3 pass 260 °C reflow	1	Precondition	0 / 231
			2	Precondition	0 / 231
			3	Precondition	0 / 231
THB (Temperature Humidity Bias)	JESD22-A101	85 °C 85 %RH With Bias Static	1	1000 Hours	0 / 77
			2	1000 Hours	0 / 77
			3	1000 Hours	0 / 77
Temperature Cycle	JESD22-A104	Condition C -65°C +150°C air to air	1	500 Cycles	0 / 77
			2	500 Cycles	0 / 77
			3	500 Cycles	0 / 77
Tomography (CSAM)	J-STD-035		1	Post Temp Cycle	0 / 11
			2	Post Temp Cycle	0 / 11
			3	Post Temp Cycle	0 / 11
Autoclave/PPOT	JESD22-A102	121 °C 100% R.H.	1	96 Hours	0 / 77
			2	96 Hours	0 / 77
			3	96 Hours	0 / 77
Solderability	JESD22-B102	93 °C steam aging 8 Hours 260 °C solder bath 5 Seconds	1	Solderability	0 / 14
HTSL (High Temperature Storage Life)	JESD22-A103	150 °C	1	1000 Hours	0 / 77



	Title: CUSTOMER PROCESS CHANGE NOTIFICATION FORM		
	Digitally Signed By:	Doc No: 4-QUAL-00017	Rev: D

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